

**Session 1 – TAPA 1/2/3**  
**Joint Plenary Session**  
Tuesday, June 19, 8:10 a.m.

**8:05 a.m.      Joint Welcome and Opening Remarks**  
Mukesh Khare, IBM  
Gunther Lehmann, Infineon

**Technology Plenary**

**T1.1 – 8:40 a.m.**

**Memory Technology: The Core to Enable Future Computing Systems**, Scott J. DeBoer, Micron Technology, Inc.

**9:20 a.m.      EDS Remarks, Fellows Recognition**  
Fernando Guarin, EDS President  
Mukesh Khare, Technology General Chair

**T1.2: 9:30 a.m.**

**Revolutionizing Cancer Genomic Medicine by AI and Supercomputer with Big Data**, Satoru Miyano, University of Tokyo

**10:10 a.m.      Break**

**Circuits Plenary**

**10:30 a.m.      Best Student Paper Awards and IEEE Awards**  
Gunther Lehmann, Infineon  
Mukesh Khare, IBM

**C1.1 - 10:40 a.m.**

**Hardware-Enabled Artificial Intelligence**, Bill Dally, Nvidia

**11:20 a.m.      2019 Joint Announcement**  
Makoto Ikeda, University of Tokyo  
Meishoku Masahara, AIST

**C1.2 - 11:30 a.m.**

**Semiconductor Technologies Accelerate Our Future Vision: “ANSHIN Platform”**, Tsuneo Komatsuzaki, SECOM

**Session 2 - TAPA 1**  
**SRAM Designs**  
Tuesday, June 19, 1:30 p.m.

Co-Chairs:      A. Loke, Qualcomm  
                    J. Chang, TSMC

**C2-1 - 1:30 p.m.**

**A 290mV Ultra-Low Voltage One-Port SRAM Compiler Design Using a 12T Write Contention and Read Upset Free Bit-Cell in 7nm FinFET Technology**, M. E. Sinangil, Y.-T. Lin, H.J. Liao, J. Chang, TSMC

**C2-2 - 1:55 p.m.**

**A 7nm Double-Pumped 6R6W Register File for Machine Learning Memory**, H. Nguyen, J. Jeong, F. Atallah, M. Jansen, A. Polomik, D. Yingling, H. Akkaraju, B. Appel, R. Nadkarni, K. Bowman, Qualcomm Technologies Inc.

**C2-3 - 2:20 p.m.**

**Half-and-Half Compare Content Addressable Memory with Charge-Sharing based Selective Match-Line Precharge Scheme**, W. Choi, H. Kim\*, C. Park\*, T. Song\*, J. Park, Korea University, \*Samsung Electronics

**C2-4 - 2:45 p.m.**

**12-nm Fin-FET 3.0G-search/s 80-bit x 128-Entry Dual-port Ternary CAM**, Makoto Yabuuchi, Masao Morimoto, Koji Nii, and Shinji Tanaka, Renesas Electronics Corporation

### **Session 3 - Honolulu**

#### **Wireless Systems**

Tuesday, June 19, 1:30 p.m.

Co-Chairs: A. Zolfaghari, Broadcom  
H. Song, POSTECH

**C3-1 - 1:30 p.m.**

**A Dual-Mode Configurable RF-to-Digital Receiver in 16nm FinFET**, A. Whitcombe, F. Sheikh\*, E. Alpman\*, A. Ravi\*, B. Nikolic, UC Berkeley, \*Intel Corporation

**C3-2 - 1:55 p.m.**

**An 113dB-Link-Budget Bluetooth-5 SoC with an 8dBm 22%-Efficiency TX**, T. Wang, Y. Ogasawara, Y. Tuda, T. Ta\*, M. Oshiro, J. Ihara, T. Maruyama, T. Hashimoto, A. Sai\*, Takashi Tokairin, Toshiba Electronic Devices & Storage Corporation, \*Toshiba Corporation

**C3-3 - 2:20 p.m.**

**Fully Integrated OOK-powered Pad-less Deep Sub-wavelength-sized 5-GHz RFID With on-chip Antenna Using Adiabatic Logic in 0.18 $\mu$ m CMOS**, Y. Toeda, T. Fujimaki, M. Hamada, T. Kuroda, Keio University

**C3-4 - 2:45 p.m.**

**A Fast Triple-Interferer Sensor (Detector and Digital Encoder) with In-Situ Reference Frequency Acquisition at 2.7-to-3.7GHz in 0.13 $\mu$ m CMOS**, D. Shin, \* K.-J. Koh\*, Virginia Tech, \*Intel Corp, also with Intel

### **Session 4 - TAPA 1**

#### **Machine Learning Processors**

Tuesday, June 19, 3:25 p.m.

Co-Chairs: D. Sylvester, University of Michigan  
M. Hashimoto, Osaka University

**C4-1 - 3:25 p.m.**

**STICKER: A 0.41-62.1 TOPS/W 8bit Neural Network Processor with Multi-Sparsity Compatible Convolution Arrays and Online Tuning Acceleration for Fully Connected Layers**, Z. Yuan, J. Yue, H. Yang, Z. Wang, J. Li, Y. Yang, Q. Guo, X. Li, M.-F. Chang\*, H. Yang, Y. Liu, Tsinghua University, \*National Tsing Hua University

**C4-2 - 3:50 p.m.**

**A Scalable Multi-TeraOPS Deep Learning Processor Core for AI Training and Inference**, B. Fleischer, S. Shukla, M. Ziegler, J. Silberman, J. Oh, V. Srinivasan, J. Choi, S. Mueller, A. Agrawal, T. Babinsky, N. Cao, C.-Y. Chen, P. Chuang, T. Fox, G. Gristede, M. Guillorn, H. Haynie, M. Klaiber, D. Lee, S. Lo, G. Maier, M. Scheuermann, S. Venkataramani, C. Vezyrtzis, N. Wang, F. Yee, C. Zhou, P.-F. Lu, B. Curran, L. Chang, K. Gopalakrishnan, IBM TJ Watson Research Center,

**C4-3 - 4:15 p.m.**

**An Ultra-high Energy-efficient reconfigurable Processor for Deep Neural Networks with Binary/Ternary Weights in 28nm CMOS**, S. Yin, P. Ouyang\*, J. Yang, T. Lu, X. Li, L. Liu, S. Wei, Tsinghua University, \*Beihang University

**C4-4 - 4:40 p.m.**

**2.9TOPS/W Reconfigurable Dense/Sparse Matrix-Multiply Accelerator with Unified INT8/INT16/FP16 Datapath in 14nm Tri-gate CMOS**, M. Anders, H. Kaul, S. Mathew, V. Suresh, S. Satpathy, A. Agarwal, S. Hsu, R. Krishnamurthy, Intel Corporation

**C4-5 - 5:05 p.m.**

**New Generation Dynamically Reconfigurable Processor Technology for Accelerating Embedded AI Applications (Invited)**, T. Fujii, T. Toi, T. Tanaka, K. Togawa, T. Kitaoka, K. Nishino, N. Nakamura, H. Nakahara\*, and M. Motomura\*\*  
Renesas Electronics Corporation, \*Tokyo Institute of Technology, \*\*Hokkaido University

**Session 5 - HONOLULU SUITE**  
**Extreme Wireline Transceivers**  
Tuesday, June 19, 3:25 p.m.

Co-Chairs: J. Proesel, IBM  
J. Lee, National Taiwan University

**C5-1 - 3:25 p.m.**

**A 112-Gb/s PAM4 Transmitter in 16nm FinFET**, K. Tan, P.-C. Chiang, Y. Wang, H. Zhao, A. Roldan, H. Zhao, N. Narang, S. Lim, D. Carey, S. Ambatipudi, P. Upadhyaya, Y. Frans, K. Chang, Xilinx

**C5-2 - 3:50 p.m.**

**112Gb/s PAM4 Wireline Receiver using a 64-way Time-Interleaved SAR ADC in 16nm FinFET**, J. Hudner, D. Carey, R. Casey, K. Hearne, P. Neto, I. Chlis, M. Erett, C. Poon, A. Laraba, H. Zhang, S. Ambatipudi, D. Mahashin, P. Upadhyaya, Y. Frans, K. Chang. Xilinx Incorporated

**C5-3 - 4:15 p.m.**

**An Active Copper-Cable Supporting 56-Gbit/s PAM4 and 28-Gbit/s NRZ with Continuous Time Linear Equalizer IC for 10-meters Reach Interconnection (Invited)**, K. Maeda, T. Norimatsu, K. Kogo, N. Kohmu, K. Nishimura\* and I. Fukasaku\*  
Hitachi, Ltd. Research and Development Group, \*Hitachi Metals, Ltd. Cable Materials Company

**C5-4 - 4:40 p.m.**

**A 64 Gb/s 1.5 pJ/bit PAM-4 Transmitter with 3-Tap FFE and Gm-Regulated Active-Feedback Driver in 28 nm CMOS**, H. Ju, M-C. Choi, G-S. Jeong, D-K. Jeong, Seoul National University

**C5-5 - 5:05 p.m.**

**A 0.3pJ/bit 112Gb/s PAM4 1+0.5D TX-DFE Precoder and 8-tap FFE in 14nm CMOS**, T. Toifl, C. Menolfi, M. Braendli, A. Cervero, P.A. Francese, M. Kossel, L. Kull, D. Luu\*, T. Morf, I. Oezkaya, IBM, \*ETH Zurich and IBM

**Session 6 - TAPA 1**  
**Adaptive and Application Specific Digital Circuits**  
Wednesday, June 20, 8:10 a.m.

Co-Chairs: E. Beigne, CEA LETI  
M. Yamaoka, Hitachi, Ltd.

**C6-1 - 8:10 a.m.**

**Memory Expansion Technology for Large-Scale Data Processing Using Software-Controlled SSD (Invited)**, E. Yoshida, S. Kazama, S. Kuwamura, S. Gokita, T. Miyoshi, Y. Noguchi, and Y. Honda\*, Fujitsu Laboratories Ltd., \*Fujitsu Ltd.

**C6-2 - 8:35 a.m.**

**An Out-of-Order RISC-V Processor with Resilient Low-Voltage Operation in 28 nm CMOS**, P.-F. Chiu, C. Celio, K. Asanovic, D. Patterson, B. Nikolic, University of California, Berkeley

**C6-3 - 9:00 a.m.**

**An Adaptive Body-Biasing SoC Using *in situ* Slack Monitoring for Runtime Replica Calibration**, M. Saligane, J. Lee, Qing Dong, M. Yasuda\*, K. Kumeno\*, F. Ohno\*, S. Miyoshi\*\*, M. Kawaminami\*/\*\*, D. Blaauw, D. Sylvester, University of Michigan, \*Mie Fujitsu Semiconductor Limited, \*\*Fujitsu Semiconductor Electronics, Inc.

**C6-4 - 9:25 a.m.**

**An All-Digital Unified Clock Frequency and Switched-Capacitor Voltage Regulator for Variation Tolerance in a Sub-Threshold ARM Cortex M0 Processor**, F. Rahman, S. Kim, N. John, R. Kumar, R. Pamula, K. Bowman\*, Visvesh Sathe University of Washington, \*Qualcomm Technologies Inc.

**Session 7 - HONOLULU SUITE**  
**Time-of-Flight and Advanced Image Sensors**  
Wednesday, June 20, 8:10 a.m.

Co-Chairs: H. Lee, Google  
Y. Oike, Sony Semiconductor Solutions Corp.

**C7-1 - 8:10 a.m.**

**A 252 × 144 SPAD Pixel FLASH LiDAR with 1728 Dual-clock 48.8 ps TDCs, Integrated Histogramming and 14.9-to-1 Compression in 180nm CMOS Technology**, S. Lindner, C. Zhang\*, I. Antolovic\*, M. Wolf\*\*, E. Charbon\*\*\*, EPFL/University of Zurich, \*TUDelft, \*\*University of Zurich, \*\*\*EPFL/TUDelft

**C7-2 - 8:35 a.m.**

**A 220 m-Range Direct Time-of-Flight 688 × 384 CMOS Image Sensor with Sub-Photon Signal Extraction (SPSE) Pixels Using Vertical Avalanche Photo-Diodes and 6 kHz Light Pulse Counters**, S. Koyama, M. Ishii, S. Saito, M. Takemoto, Y. Nose, A. Inoue, Y. Sakata, Y. Sugiura, M. Usuda, T. Kabe, S. Kasuga, M. Mori, Y. Hirose, A. Odagawa, T. Tanaka, Panasonic Corporation

**C7-3 - 9:00 a.m.**

**Multipurpose, Fully-Integrated 128x128 Event-Driven MD-SiPM with 512 16-bit TDCs with 45 ps LSB and 20 ns Gating**, A. Carimatto, A. Ulku, S. Lindner\*, E. D'Aillon, S. Pellegrini\*\*, B. Rae\*\*, E. Charbon\*, TU Delft, \*EPFL, \*\*ST Microelectronics

**C7-4 - 9:25 a.m.**

**A Two-Tap NIR Lock-In Pixel CMOS Image Sensor with Background Light Cancelling Capability for Non-Contact Heart Rate Detection**, C. Cao, Y. Shirakawa, L. Tan, M. W. Seo, K. Kagawa, K. Yasutomi, T. Kosugi\*, S. Aoyama\*, N. Teranishi, N. Tsumura\*\*, S. Kawahito, Shizuoka University, \*Brookman Technology, \*\*Chiba University

**Session 8 - TAPA 1**  
**Joint Focus Session: Emerging Memory**  
Wednesday, June 20, 10:05 a.m.

Co-Chairs: E. Wang, Intel Corp.  
N. Lu, Etron Technology, Inc.

**C8-1 - 10:05 a.m.**

**Logic Process Compatible 40nm 16Mb, Embedded Perpendicular-MRAM with Hybrid-Resistance Reference, sub- $\mu$ A Sensing Resolution, and 17.5ns Read Access Time**, Y.-C. Shih, C.-F. Lee, Y.-A. Chang, P.-H. Lee, H.-J. Lin, Y.-L. Chen, K.-F. Lin, T.-C. Yeh, H.-C. Yu, H. Chuang, Y.-D. Chih, J. Chang, TMSC

**C8-2 - 10:30 a.m.**

**SOT-MRAM 300mm Integration for Low Power and Ultrafast Embedded Memories**, K. Garello, F. Yasin, S. Couet, L. Souriau, J. Swerts, S. Rao, S. Van Beek, W. Kim, E. Liu, S. Kundu, D. Tsvetanova, N. Jossart, K. Croes, E. Grimaldi\*, M. Baumgartner\*, D. Crotti, A. Furnémont, P. Gambardella\*, G. S. Kar, imec, \*ETHC

**C8-3 - 10:55 a.m.**

**High-speed Voltage Control Spintronics Memory (VoCSM) Having Broad Design Windows**, N. Shimomura, H. Yoda, T. Inokuchi, K. Koi, H. Sugiyama, Y. Kato, Y. Ohsawa, A. Buyandalai, S. Shirotori, S. Oikawa, M. Shimizu, M. Ishikawa, T. Ajay, and A. Kurobe, Toshiba Corp.

**C8-4 - 11:20 a.m.**

**Energy Efficient Adiabatic FRAM with 0.99 pJ/bit Write for IoT Applications**, S. Jeloka, Z. Wang, R. Xie\*\*, S. Khanna\*\*\*, S. Bartling\*\*\*, D. Sylvester, D. Blaauw, University of Michigan, \*ARM, \*\*AMD, \*\*\*Texas Instruments

**C8-5 - 11:45 a.m.**

**14nm FinFET 1.5Mb Embedded High-K Charge Trap Transistor One Time Programmable Memory Using Dynamic Adaptive Programming**, E. Hunt-Schroeder, D. Anand, J. Fifield, M. Jacunski, M. Roberge, D. Pontius, K. Batson, T. Kirihata, GLOBALFOUNDRIES

### **Session 9 - HONOLULU SUITE**

#### **Nyquist ADC**

Wednesday, June 20, 10:05 a.m.

Co-Chairs: R. Kapusta, Analog Devices  
C. Liu, MediaTek, Inc.

**C9-1 - 10:05 a.m.**

**A 12-bit 31.1uW 1MS/s SAR ADC with On-Chip Input-Signal-Independent Calibration Achieving 100.4dB SFDR using 256fF Sampling Capacitance**, J. Shen, A. Shikata, A. Liu, F. Chalifoux, Analog Devices

**C9-2 - 10:30 a.m.**

**A 0.5-1.1V 10b Adaptive Bypassing SAR ADC Utilizing Oscillation Cycle Information of VCO-based Comparator**, Z. Ding, X. Zhou, Q. Li, University of Electronic Science and Technology of China

**C9-3 - 10:55 a.m.**

**A 2.3-mW, 950-MHz, 8-bit Fully-Time-Based Subranging ADC Using Highly-Linear Dynamic VTC**, K. Ohhata, Kagoshima University

**C9-4 - 11:20 a.m.**

**A >3GHz ERBW 1.1-GS/s 8-bit Two-Step SAR ADC with Recursive-Weight DAC**, H. Chen, X. Zhou, Q. Yu, F. Zhang, Q. Li, University of Electronic Science and Technology of China

**C9-5 - 11:45 a.m.**

**A 13bit 5GS/s ADC with time-interleaved chopping calibration in 16nm FinFET**, B. Vaz, B. Verbruggen, C. Erdmann, D. Collins, J. Mcgrath, A. Boumaalif, E. Cullen, D. Walsh, A. Morgado, C. Mesadri, B. Long, R. Pathepuram, R. De La Torre, A. Manlapat, G. Karyotis, D. Tsaliagos, P. Lynch, P. Lim, D. Breathnach and B. Farley, Xilinx

### **Session 10 - TAPA 1**

#### **Joint Focus Session: Power Devices and Circuits**

Wednesday, June 20, 1:30 p.m.

Co-Chairs: Y. Ramadass, Texas Instruments  
P. Yue, Hong Kong University of Science and Technology

**C10-1 - 1:30 p.m.**

**A Single-Topology Continuously-Scalable-Conversion-Ratio Fully Integrated Switched-Capacitor DC-DC Converter with 0-to-2.22V Output and 93% Peak-Efficiency**, N. Butzen, M. Steyaert, KU Leuven

**C10-2 - 1:55 p.m.**

**New Methodology for Evaluating Minority Carrier Lifetime for Process Assessment**, K. Kakushima, T. Hoshii, M. Watanabe, N. Shigyo, K. Furukawa, T. Saraya\*, T. Takakura\*, K. Itou\*, M. Fukui\*, S. Suzuki\*, K. Takeuchi\*, I. Muneta, H.

Wakabayashi, Y. Numasawa\*\*, A. Ogura\*\*, S. Nishizawa\*\*\*, K. Tsutsui, T. Hiramoto\*\*, H. Ohashi, and H. Iwai, Tokoyo Institute of Technology, \*The University of Tokoyo, \*\*Meiji University, \*\*\*Kyushu University

**C10-3 - 2:20 p.m.**

**A Quasi-Digital Ultra-Fast Capacitor-less Low-Dropout Regulator Based on Comparator Control for x8 Current Spike of PCRAM systems**, Sung-Won Choi, Yeunhee Huh, Sang-Hui Park, Kye-Seok Yoon, Jun-Suk Bang, Se-Un Shin, Yong-Min Ju, Yujin Yang, Junghyuk Yoon\*, Changyong Ahn\*, Taekseung Kim\*, Sung-Wan Hong \*\*, Gyu-Hyeong Cho, KAIST, \*SK Hynix Semiconductor, \*\*Sookmyung Women's University

**C10-4 - 2:45 p.m.**

**0.5V-V<sub>IN</sub>, 165-mA/mm<sup>2</sup> Fully-Integrated Digital LDO based on Event-Driven Self-Triggering Control**, D. Kim, S. Kim, H. Ham\*, J. Kim\*, M. Seok, Columbia University, \*SK Hynix

**Session 11 - HONOLULU 1**

**Frequency References**

Wednesday, June 20, 1:30 p.m.

Co-Chairs: C. Sander, Infineon  
Y. Bando, Socionext, Inc.

**C11-1 - 1:30 p.m.**

**A CMOS Molecular Clock Probing 231.061-GHz Rotational Line of OCS with Sub-ppb Long-Term Stability and 66-mW DC Power**, C. Wang, X. Yi, M. Kim, Y. Zhang, R. Han, Massachusetts Institute of Technology

**C11-2 - 1:55 p.m.**

**A 64 $\mu$ s Start-Up 26/40MHz Crystal Oscillator with Negative Resistance Boosting Technique Using Reconfigurable Multi-Stage Amplifier**, M. Miyahara, Y. Endo\*, K. Okad\*\*, A. Matsuzawa\*, High Energy Accelerator Research Organization, \*Tokyo Institute of Technology

**C11-3 - 2:20 p.m.**

**A 224 pW 260 ppm/°C Gate-Leakage-based Timer for Ultra-Low Power Sensor Nodes with Second-Order Temperature Dependency Cancellation**, J. Lim, T. Jang, M. Saligane, M. Yasuda\*, S. Miyoshi\*\*, M. Kawaminami, D. Blaauw, D. Sylvester, University of Michigan, \*Mie Fujitsu Semiconductor Limited, \*\*Fujitsu Electronics America

**C11-4 - 2:45 p.m.**

**A Sub-Leakage pW-Power Hz-Range Relaxation Oscillator Operating with 0.3V-1.8V Unregulated Supply**, O. Aiello, P. Crovetto\*, M. Alioto, National University of Singapore, \*Politecnico di Torino

**Session 12 - HONOLULU 2**

**Bio-Medical Interfaces**

Wednesday, June 20, 1:30 p.m.

Co-Chairs: D. Markovic, University of California, Los Angeles  
T. Tokuda, Nara Institute of Science and Technology

**C12-1 - 1:30 p.m.**

**A 0.8V 82.9 $\mu$ W In-Ear BCI Controller System with 8.8 PEF EEG Instrumentational Amplifier and Wireless BAN Transceiver**, J. Lee, K.-R. Lee, U. Ha\*, J.-H. Kim, K. Lee, H.-J. Woo, KAIST, \*MIT Media Lab

**C12-2 - 1:55 p.m.**

**A Battery-Powered Opto-Electrophysiology Neural Interface with Artifact-Preventing Optical Pulse Shaping**, A. Mendrela, S.-Y. Park, M. Vöröslakos, M. Flynn, and E. Yoon, University of Michigan

**C12-3 - 2:20 p.m.**

**Artifact-Tolerant Opamp-less Delta-Modulated Bidirectional Neuro-Interface**, M. R. Pazhouhandeh, H. Kassiri, A. Shoukry, I. Wesspapier\*, P. Carlen\*, R. Genov, University of Toronto, \*Toronto Western Hospital

**C12-4 - 2:45 p.m.**

**A 400GΩ Input-impedance, 220mV<sub>pp</sub> Linear-input-range, 2.8V<sub>pp</sub> CM-interference-tolerant active electrode for Non-contact Capacitively Coupled ECG acquisition**, Mingyi Chen, Ivan Dario Castro, Qiuyang Lin, Tom Torfs, Filip Tavernier\*, Chris Van Hoof, Nick Van Helleputte, imec, \*KU Leuven

### Session 13 - TAPA 1

#### Robotics and Machine Learning applications

Wednesday, June 20, 3:25 p.m.

Co-Chairs: B. Nikolic, University of California, Berkeley  
K. Sohn, Samsung Electronics Co., Ltd.

**C13-1 - 3:25 p.m.**

**Navion: A Fully Integrated Energy-Efficient Visual-Inertial Odometry Accelerator for Autonomous Navigation of Nano Drones**, A. Suleiman, Z. Zhang, L. Carlone, S. Karman, V. Sze, Massachusetts Institute of Technology

**C13-2 - 3:50 p.m.**

**A 1920 × 1080 25fps, 2.4TOPS/W Unified Optical Flow and Depth 6D Vision Processor for Energy-Efficient, Low Power Autonomous Navigation**, Ziyun Li, Jingcheng Wang, Dennis Sylvester, David Blaauw, and Hun-Seok Kim, University of Michigan

**C13-3 - 4:15 p.m.**

**B-Face: 0.2 mW CNN-Based Face Recognition Processor with Face Alignment for Mobile User Identification**, S. Kang, J. Lee, C. Kim, H. Yoo, KAIST

**C13-4 - 4:40 p.m.**

**A 141 uW, 2.46 pJ/Neuron Binarized Convolutional Neural Network based Self-learning Speech Recognition Processor in 28nm CMOS**, Shouyi Yin, Peng Ouyang\*, Shixuan Zheng, Dandan Song, Xiudong Li, Leibo Liu, Shaojun Wei, Tsinghua University, \*Beihang University

**C13-5 - 5:05 p.m.**

**A Mixed-Signal Binarized Convolutional-Neural-Network Accelerator Integrating Dense Weight Storage and Multiplication for Reduced Data Movement**, H. Valavi, P. Ramadge, E. Nestler\*, and N. Verma, Princeton University, \*Analog Devices Inc.

### Session 14 - HONOLULU 1

#### Advanced Wireline and Memory Interfaces

Wednesday, June 20, 3:25 p.m.

Co-Chairs: E. Naviasky, Cadence  
Y. Takai, Micron Memory Japan

**C14-1 - 3:25 p.m.**

**A 0.5-28Gb/s Wireline Transceiver with 15-Tap DFE and Fast-Locking Digital CDR in 7nm FinFET**, J. Im, S. Chen, D. Freitas, A. Chou, L. Zhou, I. Zhuang, T. Cronin, D. Mahashin, W. Lin, K. L. Chan, H. Zhao, K. H. Tan, A. Bekele, D. Turker, P. Upadhyaya, Y. Frans, K. Chang, Xilinx Inc.

**C14-2 - 3:50 p.m.**

**A sub-0.85V, 6.4Gbp/s/pin TX-Interleaved Transceiver with Fast Wake-up Time using 2-Step Charging Control and V<sub>OH</sub> Calibration in 20nm DRAM Process**, J.-H. Baek, C.-K. Lee, K. Kim, D.-S. Moon, G.-H. Cha, J.-S. Heo, M. Ahn, D.-J. Kim, J.-J. Song, S. Kwon, J. Kim, K.-S.oo Kim, J. Ahn, J.-S. Nam, B. Kim, J.-H. Cho, J.-H. Oh, S.-J. Bae, I. Song, S.-H. Hyun, I. Kim, H.-J. Kwon, Y.-S. Sohn, J.-H. Choi, K.-I. Park, S.-J. Jang, Samsung Electronics

**C14-3 - 4:15 p.m.**

**A 12.8 Gb/s Daisy Chain-Based Downlink I/F Employing Spectrally Compressed Multi-Band Multiplexing for High-Bandwidth and Large-Capacity Storage Systems**, Y. Tsubouchi, D. Miyashita, Y. Satoh, T. Toi, F. Tachibana, M. Morimoto, J. Wadatsumi, J. Deguchi, Toshiba Memory Corporation

**C14-4 - 4:40 p.m.**

**A Digital-Intensive 2-to-9.2 Gb/s/pin Memory Controller I/O with Fast-Response LDO in 10nm CMOS**, R. Inti, M. Mansuri, J. Kennedy, H. Venkatram, C.-M. Hsu, A. Martin, J. Jaussi, B. Casper, Intel Corporation

**C14-5 - 5:05 p.m.**

**An Automated SerDes Frontend Generator Verified with a 16nm Instance Achieving 15 Gb/s at 1.96 pJ/bit**, E. Chang, N. Narevsky, J. Han, E. Alon, University of California, Berkeley

**Session 15 - HONOLULU 2**  
**Capacitive Sensor Interfaces**  
Wednesday, June 20, 3:25 p.m.

Co-Chairs: K. Makinwa, Delft University of Technology  
Y. Xu, National University of Singapore

**C15-1 - 3:25 p.m.**

**A 114-aF<sub>rms</sub>-Resolution 46-nF/10-M $\Omega$ -Range Digital-Intensive Reconfigurable RC-to-Digital Converter with Parasitic-Insensitive Femto-Farad Baseline Sensing**, A. George, W. Shim, M. Je\* and J. Lee, DGIST, \*KAIST

**C15-2 - 3:50 p.m.**

**A 117dB In-band CMRR 98.5dB SNR Capacitance-to-Digital Converter for Sub-nm Displacement Sensing with an Electrically Floating Target**, H. Jiang, S. Amani, J. Vogel, S. Shalmany, and S. Nihtianov, Delft University of Technology

**C15-3 - 4:15 p.m.**

**A 181nW 970 $\mu$ g/VHz Accelerometer Analog Front-End Employing Feedforward Noise Reduction Technique**, I. Akita, T. Okazawa, Y. Kurui\*, A. Fujimoto\*, T. Asano, Toyohashi University of Technology, \*Toshiba Corporation

**C15-4 - 4:40 p.m.**

**A 2.69 $\mu$ W Dual Quantization-based Capacitance-to-Digital Converter for Pressure, Humidity, and Acceleration Sensing in 0.18 $\mu$ m CMOS**, S.Park, G.H.Lee, S.H.Cho, KAIST

**C15-5 - 5:05 p.m.**

**An 8.2  $\mu$ W 0.14 mm<sup>2</sup> 16-Channel CDMA-Like Period Modulation Capacitance-to-Digital Converter with Reduced Data Throughput**, Yuxuan Luo, Chun-Huat Heng, National University of Singapore

**Session 16 - TAPA 1**  
**Hardware Security**  
Thursday, June 21, 8:10 a.m.

Co-Chairs: B. Calhoun, University of Virginia  
N. Miura, Kobe University

**C16-1 - 8:10 a.m.**

**An All-Digital Unified Static/Dynamic Entropy Generator Featuring Self-Calibrating Hierarchical Von Neumann Extraction for Secure Privacy-Preserving Mutual Authentication in IoT Mote Platforms**, S. Satpathy, S. Mathew, V. Suresh, M. Anders, H. Kaul, A. Agarwal, S. Hsu, R. Krishnamurthy, V. De, Intel Corporation

**C16-2 - 8:35 a.m.**



**A 28nm Integrated True Random Number Generator Harvesting Entropy from MRAM**, K. Yang, Q. Dong, Z. Wang, Y.-C. Shih\*, Y.-D. Chih\*, J. Chang\*, D. Blaauw, D. Sylvester, University of Michigan, \*TSMC

**C16-3 - 9:00 a.m.**

**An All-Digital True-Random-Number Generator with Integrated De-correlation and Bias-Correction at 3.2-to-86 Mb/s, 2.58 pJ/bit in 65 nm CMOS**, V. Rajesh Pamula, Xun Sun, Sung Kim, Fahim ur Rahman, Baosen Zhang and Visvesh Sathe, University of Washington

**C16-4 - 9:25 a.m.**

**220mV-900mV 794/584/754 Gbps/W Reconfigurable GF(2<sup>4</sup>)<sup>2</sup> AES/SMS4/Camellia Symmetric-Key Cipher Accelerator in 14nm Tri-gate CMOS**, S. Satpathy, V. Suresh, S. Mathew, M. Anders, H. Kaul, A. Agarwal, S. Hsu, R. Krishnamurthy, Intel Corporation

### **Session 17 - HONOLULU 1**

#### **Advanced PLLs**

Thursday, June 21, 8:10 a.m.

Co-Chairs: E. Jassen, NXP Semiconductors  
K. Agawa, Toshiba Corp.

**C17-1 - 8:10 a.m.**

**A Digital Bang-Bang Phase-Locked Loop with Background Injection Timing Calibration and Automatic Loop Gain Control in 7nm FinFET CMOS**, T.-K. Kuan, C.-Y. Wu, R.-P. Shen, C.-H. Chang, K. Hsieh, M. Chen, Taiwan Semiconductor Manufacturing Company

**C17-2 - 8:35 a.m.**

**AMASS PLL: An Active-Mixer-Adopted Sub-Sampling PLL Achieving an FOM of -255.5dB and a Reference Spur of -66.5dBc**, D. Lee, P. Mercier, University of California, San Diego

**C17-3 - 9:00 a.m.**

**A 0.2GHz to 4GHz Hybrid PLL (ADPLL/Charge-Pump-PLL) in 7nm FinFET CMOS Featuring 0.619ps Integrated Jitter and 0.6us Settling Time at 2.3mW**, T.-H. Tsai, R.-B. Sheen, C.-H. Chang, R. Staszewski\*, Taiwan Semiconductor Manufacturing Company, \*University College Dublin

**C17-4 - 9:25 a.m.**

**153 fs<sub>RMS</sub>-Integrated-Jitter and 114-Multiplication Factor PVT-Robust 22.8 GHz Ring-LC-Hybrid Injection-Locked Clock Multiplier**, S. Choi, S. Yoo, Y. Lee, Y. Jo, J. Lee, Y. Lim, J. Choi, Ulsan National Institute of Science and Technology

### **Session 18 - HONOLULU 2**

#### **Wireless for Biomedical and IoT**

Thursday, June 21, 8:10 a.m.

Co-Chairs: C. Lopez, imec  
T. Nezuka, Denso Corp.

**C18-1 - 8:10 a.m.**

**A Wireless Implantable Ultrasound Array Receiver for Thermoacoustic Imaging**, A. Sawaby, M. L. Wang, E. So, J.-C. Chien, H. Nan, B. T. Khuri-Yakub, A. Arbabian, Stanford University

**C18-2 - 8:35 a.m.**

**A 0.04mm<sup>3</sup> 16nW Wireless and Batteryless Sensor System with Integrated Cortex-M0+ Processor and Optical Communication for Cellular Temperature Measurement**, X. Wu, I. Lee, Q. Dong, K. Yang, D. Kim, J. Wang, Y. Peng, Y. Zhang, M. Saligane, M. Yasuda\*, K. Kumeno\*, F. Ohno\*, S. Miyoshi\*\*, M. Kawaminami\*, D. Sylvester & D. Blaauw  
1University of Michigan, \*Mie Fujitsu Semiconductor Limited, \*\*Fujitsu Electronics America, Inc.

**C18-3 - 9:00 a.m.**

**Self-Regulated Wireless Power and Simultaneous 5 Mb/s Reverse Data over One Pair of Coils**, J. Pan, A. A. Abidi, W. Jiang, D. Rozgic, D. Markovic, University of California, Los Angeles

**C18-4 - 9:25 a.m.**

**A Single-Stage, Single-Inductor, 6-Input 9-Output Multi-Modal Energy Harvesting Power Management IC for 100 $\mu$ W-120mW Battery-Powered IoT Edge Nodes**, Suhwan Kim, Vaibhav Vaidya, Christopher Schaefer, Andrew Lines, Harish Krishnamurthy, Sheldon Weng, Xiaosen Liu, Dileep Kurian, Tanay Karnik, Krishnan Ravichandran, James Tschanz, Vivek De, Intel Corporation

**Session 19 - TAPA 1**  
**Oversampling Data Converters**  
Thursday, June 21, 10:05 a.m.

Co-Chairs: E. Martens, imec  
M. Fukazawa, Renesas Electronics Corp.

**C19-1 - 10:05 a.m.**

**A 1.2V 68 $\mu$ W 98.2dB-DR Audio Continuous-Time Delta-Sigma Modulator**, C. Lee, M. Jang, Y. Chae, Yonsei University

**C19-2 - 10:30 a.m.**

**A 0.029mm<sup>2</sup> 17-fJ/Conv.-Step CT  $\Delta\Sigma$  ADC With 2<sup>nd</sup>-Order Noise-Shaping SAR Quantizer**, Jiaxin Liu, Shaolan Li\*, Wenjuan Guo\*, Guangjun Wen, Nan Sun\*, University of Electronic Science and Technology of China, \*The University of Texas at Austin

**C19-3 - 10:55 a.m.**

**A 77dB SNDR 12.5MHz Bandwidth 0-1 MASH  $\Sigma\Delta$  ADC Based on the Pipelined-SAR Structure**, Y. Song, Y. Zhu, C.-H. Chan, L. Geng\*, R. P. Martins, University of Macau, \*Xi'an Jiaotong University

**C19-4 - 11:20 a.m.**

**A 1.25MS/s Two-Step Incremental ADC with 100dB DR and 110dB SFDR**, T. Katayama, S. Miyashita, K. Sobue, K. Hamashita, Asahi Kasei Microdevices

**C19-5 - 11:45 a.m.**

**A 550 $\mu$ W 20kHz BW 100.8dB SNDR Linear-Exponential Multi-Bit Incremental Converter with 256-cycles in 65nm CMOS**, B. Wang, S.-W. Sin, S.-P. U\*, F. Maloberti\*\*, R. P. Martins, University of Macau, \*Synopsys Macau Ltd. \*\* University of Pavia

**Session 20 - HONOLULU 1**  
**RF Circuits and Techniques**  
Thursday, June 21, 10:05 a.m.

Co-Chairs: M. Chen, University of Southern California  
H. Shin, Kwangwoon University

**C20-1 - 10:05 a.m.**

**Terahertz RF Front-End Employing Even-Order Subharmonic MOS Symmetric Varactor Mixers in 65-nm CMOS for Hydration Measurements at 560 GHz**, Q. Zhong, W. Choi, K. O, The University of Texas at Dallas

**C20-2 - 10:30 a.m.**

**A Sub-Harmonic Switching Digital Power Amplifier with Hybrid Class-G Operation for Enhancing Power Back-off Efficiency**, A. Zhang, M. Chen, University of Southern California

**C20-3 - 10:55 a.m.**

**A 5.5 GHz Background-Calibrated Subsampling Polar Transmitter with -41.3 dB EVM at 1024 QAM in 28nm CMOS**, N. Markulic\*, P. Renukaswamy\*, E. Martens, B. van Liempd, P. Wambacq\*, J. Craninckx, imec; \*also at Vrije Universiteit Brussel

**C20-4 - 11:20 a.m.**

**A 16-Gb/s 0-dB Power Back-off 16-QAM Transmitter at 28 GHz in 65-nm CMOS**, X. Meng, C. Wang, M. Kalantari, C. P. Yue, The Hong Kong University of Science and Technology

**C20-5 - 11:45 a.m.**

**A modular 16nm Direct-RF TX/RX embedding 9GS/s DAC and 4.5GS/s ADC with 90dB isolation and sub-80ps channel alignment for monolithic integration in 5G base-station SoC**, C. Erdmann, B. Verbruggen, B. Vaz, R. Pelliconi, J. Mcgrath, R. Kinnerk, R. De La Torre, P. Lynch, J. O'Dwyer, P. Kelly, P. Lim, D. Breathnach, B. Farley, XILINX

**Session 21 - HONOLULU 2**  
**Power Converters**  
Thursday, June 21, 10:05 a.m.

Co-Chairs: M. Chen, ADI / Linear  
K. Kanda, Fujitsu Laboratories, Ltd.

**C21-1 - 10:05 a.m.**

**A 95.3% Peak Efficiency, 135nA Quiescent Current Buck-Boost DC-DC Converter with Current-Slope-Based Mode Control**, D. Lu, P. Liu, S. Yao, L. Wang, J. He, Analog Device Inc.

**C21-2 - 10:30 a.m.**

**A Hybrid Dual-Path Step-Down Converter with 96.2% Peak Efficiency using a 250mΩ Large-DCR Inductor**, Y. Huh, S.-U. Shin, S.-W. Hong\*, Y.-J. Woo\*\*, Y.-M. Ju, S.-W. Choi, G.-H. Cho, KAIST, \*Sookmyung Women's University, \*\*Silicon Works

**C21-3 - 10:55 a.m.**

**A 92.8% Efficiency Adaptive-On/Off-Time Control 3-Level Buck Converter for Wide Conversion Ratio with Shared Charge Pump Intermediate Voltage Regulator**, Y. Karasawa, T. Fukuoka, K. Miyaji, Shinshu University

**C21-4 - 11:20 a.m.**

**An Ultra-low Quiescent Current 250nA Low Dropout Regulator for No-load to 10mA Internet-of-Everything Applications**, S.-Q.Chen, C.-M. Huang, K.-H. Chen, Y.-H. Lin\*, S.-R. Lin\*, T.-Y. Tsai\*, National Chiao Tung University, \*Realtek Semiconductor Corporation

**C21-5 - 11:45 a.m.**

**A Fully Integrated 700mA Event-Driven Digital Low-Dropout Regulator with Residue-Tracking Loop for Fine-Grained Power Management Unit**, J.-E Park, D.-K. Jeong, Seoul National University

**Session 23 - TAPA 1**  
**Advanced Amplifiers and Analog Front-Ends**  
Thursday, June 21, 1:50 p.m.

Co-Chairs: A. Molnar, Cornell University  
M. Je, KAIST

**C22-1 - 1:50 p.m.**

**A 1mW -101dB THD+N Class-AB High-Fidelity Headphone Driver in 65nm CMOS**, N. Mehta, J. Huijsing\*, V. Stojanovic, University of California at Berkeley, \*Delft University of Technology

**C22-2 - 2:15 p.m.**

**A 2.2 NEF Neural-Recording Amplifier Using Discrete-Time Parametric Amplification**, T. Jang, K. Choo, J. Lim, S. Nason, J. Lee, S. Oh, S. Jeong, C. Chestek, D. Sylvester, D. Blaauw, University of Michigan

**C22-3 - 2:40 p.m.**

**A 6.5 $\mu$ W 92.3dB-DR Biopotential-Recording Front-End with 360mV<sub>pp</sub> Linear Input Range**, J.-S. Bang\*, H. Jeon, M. Je, G.-H. Cho, KAIST, \*also with Samsung Electronics

**C22-4 - 3:05 p.m.**

**A 0.6V 54dB SNR Analog Frontend with 0.18% THD for Low Power Sensory Applications in 65nm CMOS**, K. Badami, K. Murthy, P. Harpe\*, M. Verhelst, KU Leuven, Texas Instruments, \*Eindhoven University of Technology

**Session 22 - HONOLULU 1**

**Next Generation Sensors**

Thursday, June 21, 1:50 p.m.

Co-Chairs: A. Arbabian, Stanford University

Y. Hirose, Panasonic Corp.

**C23-1 - 1:50 p.m.**

**A 5500fps 85GOPS/W 3D stacked BSI vision chip based on parallel in-focal-plane acquisition and processing**, L. Millet, S. Chevobbe, C. Andriamisaina, E. Beigne, F. Guellec, T. Dombek, L. Benaissa, E. Deschaseaux, M. Duranton, K. Benchehida, M. Darouich, M. Lepecq, CEA

**C23-2 - 2:15 p.m.**

**A 2pJ/pixel/direction MIMO Processing based CMOS Image Sensor for Omnidirectional Local Binary Pattern Extraction and Edge Detection**, X. Zhong, Q. Yu, A. Bermak\*\*, C.-Y. Tsui, M.-K. Law\*, Hong Kong University of Science and Technology, \*University of Macau, \*\*also with Hamad Bin Khalifa University

**C23-3 - 2:40 p.m.**

**Room-Temperature Quantum Sensing in CMOS: On-Chip Detection of Electronic Spin States in Diamond Color Centers for Magnetometry**, M. Ibrahim, C. Foy, D. Kim, D. Englund, and R. Han, Massachusetts Institute of Technology

**C23-4 - 3:05 p.m.**

**A 179-lux Energy-Autonomous Fully-Encapsulated 17-mm<sup>3</sup> Sensor Node with Initial Charge Delay Circuit for Battery Protection**, I. Lee, G. Kim\*, E. Moon, S. Jeong\*, D. Kim, J. Phillips, D. Blaauw\*, University of Michigan, \*also with CubeWorks

**Session 24 - TAPA 1**

**Machine Learning for Health and Neuro Inspired Processing**

Thursday, June 21, 3:45 p.m.

Co-Chairs: V. Sze, Massachusetts Institute of Technology

H. Inoue, NEC Corp.

**C24-1 - 3:45 p.m.**

**A 4096-neuron 1M-synapse 3.8pJ/SOP Spiking Neural Network with On-chip STDP Learning and Sparse Weights in 10nm FinFET CMOS**, G. K. Chen, R. Kumar, H. E. Sumbul, P. Knag, R. K. Krishnamurthy, Intel Corporation

**C24-2 - 4:10 p.m.**

**A 0.76mm<sup>2</sup> 0.22nJ/Pixel DL-assisted 4K Video Encoder LSI for Quality-of-Experience over Smart-Phones**, Tsu-Ming Liu, Chang-Hung Tsai, Tung-Hsing Wu, Jia-Ying Lin, Li-Heng Chen, Han-Liang Chou and Chi-Cheng Ju, Mediatek Inc.

**C24-3 - 4:35 p.m.**

**A 1.9mW SVM Processor with On-chip Active Learning for Epileptic Seizure Control**, S-A. Huang, K.-C. Chang\*, H.-H. Liou\*, C.-H. Yang\*\*, National Taiwan University, \*National Taiwan University Hospital, \*\* also with National Chiao-Tung University

**C24-4 - 5:00 p.m.**

**A 12.6mW 573-2,901KS/s Reconfigurable Processor for Reconstruction of Compressively-Sensed Physiological Signals,** Y.-Z. Wang, Y.-P. Wang, Y.-C. Wu, C.-H. Yang, National Taiwan University

**C24-5 - 5:25 p.m.**

**PhaseMAC: A 14 TOPS/W 8bit GRO based Phase Domain MAC Circuit for In-Sensor-Computed Deep Learning Accelerators,** K. Yoshioka, Y. Toyama, K. Ban, D. Yashima, S. Maya, A. Sai, K. Onizuka, Toshiba

**Session 25 - HONOLULU 1**

**Wireline Building Blocks**

Thursday, June 21, 3:45 p.m.

Co-Chairs: B. Casper, Intel Corp.  
H. Katsurai, NTT Device Technology Laboratories

**C25-1 - 3:45 p.m.**

**A 50Gb/s 1.6pJ/b RX Data-Path with Quarter-Rate 3-tap Speculative DFE,** P.A. Francese, A. Cevrero, I. Ozkaya, M. Braendli, C. Menolfi, T. Morf, M. Kossel, L. Kull, D. Luu\* and T. Toifl, IBM Research-Zurich, \*also with ETH

**C25-2 - 4:10 p.m.**

**An Inverter-based Analog Front End for a 56 Gb/s PAM4 Wireline Transceiver in 16nm CMOS,** K. Zheng, Y. Frans\*, Sai L. Ambatipudi\*, S. Asuncion\*, H. Reddy\*, K. Chang\*, B. Murmann, Stanford University, \*Xilinx Inc.

**C25-3 - 4:35 p.m.**

**A 14  $\mu\text{m}$   $\times$  26  $\mu\text{m}$  20-Gb/s 3-mW CDR Circuit with High Jitter Tolerance,** Long Kong, Yikun Chang, Behzad Razavi, University of California, Los Angeles

**C25-4 - 5:00 p.m.**

**A 40Gb/s Optical NRZ Transmitter Based on Monolithic Microring Modulators in 45nm SOI CMOS,** S. Lin, S. Moazeni, V. Stojanovic, University of California, Berkeley

**C25-5 - 5:25 p.m.**

**A 10-bit 20-40 GS/s ADC with 37 dB SNDR at 40 GHz Input using First Order Sampling Bandwidth Calibration,** L. Kull\*, D. Luu\*\*, C. Menolfi, Thomas Morf, P. Francese, M. Braendli, M. Kossel, A. Cevrero, I. Ozkaya, T. Toifl. IBM Research, \*\*also with ETH